	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under b international and Pan-American copyright conventions.			under both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
1752-21.1					Form Type Distribute	*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
Supplie	r Information															
Company name* Co				Company unique ID			Unique ID Authority					Response Date*				
onsemi												2024-05-11				
Contact N	lame		Title - Contact				Phone - Contact*					Email - Contact*				
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
uthorize	ed Representative*		Title - Representative				Phone - Representative*				Email - Representative*					
Product-	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item BMS3003		n Number Mfr Item Name				Effective Date	te Version Manufacturing Site		V	Weight*	UOM	Unit Type			
			3-1E	-1E PCH 4V DRIVE SERIES			2024-05-11			1784.54		mg	Each			
/Ianufa	cturing Proccess Informa	tion														
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020		J-STD-020 MSI	L Rating	Peak Process Body Te		ody Temperatu	Temperature Max Time at Peak		Temperate	ure Numb	er of Reflow Cyc	eles	
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		С	30		second	is 3					
omments	8															
or more	information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless	otherwise noted).							
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	11.74	mg	Supplier	Silicon (Si)	7440-21-3		11.74	mg
Die Attach	5.25	mg	Supplier	Silver (Ag)	7440-22-4		0.0787	mg
			А	Lead (Pb)	7439-92-1	7a	4.9088	mg
			Supplier	Tin (Sn)	7440-31-5		0.2625	mg
Lead Frame	667.8	mg	Supplier	Iron (Fe)	7439-89-6		0.6678	mg
			Supplier	Copper (Cu)	7440-50-8		666.9319	mg
			Supplier	Phosphorus (P)	7723-14-0		0.2003	mg
Mold Compound-Black	1094.34	mg		Brominated epoxy resin	proprietary data		18.6038	mg
			Supplier	Phenolic Resin	Proprietary Data		87.5472	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		16.4151	mg
			Supplier	Carbon Black (C)	1333-86-4		2.7358	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		114.9057	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		854.1324	mg
Plating	4.5	mg	Supplier	Tin (Sn)	7440-31-5		4.5	mg
Wire Bond - Al	0.91	mg	Supplier	Aluminum (Al)	7429-90-5		0.91	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signa range of distribution unless otherwise noted).